

# E2SMA12-8.000M

[Click part number to visit Part Number Details page](#)

## REGULATORY COMPLIANCE (Data Sheet downloaded on Oct 25, 2016)


[Click badges to download compliance docs](#)

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



## ITEM DESCRIPTION

Quartz Crystal Resonator HC49/UP 2 Pad Surface Mount (SMD) 4.5mm Height Metal Resistance Weld Seal 8.000MHz  $\pm 15$ ppm at 25°C,  $\pm 20$ ppm over -40°C to +85°C 12pF Parallel Resonant

## ELECTRICAL SPECIFICATIONS

|                               |                                                        |
|-------------------------------|--------------------------------------------------------|
| Nominal Frequency             | 8.000MHz                                               |
| Frequency Tolerance/Stability | $\pm 15$ ppm at 25°C, $\pm 20$ ppm over -40°C to +85°C |
| Aging at 25°C                 | $\pm 5$ ppm/year Maximum                               |
| Load Capacitance              | 12pF Parallel Resonant                                 |
| Shunt Capacitance             | 7pF Maximum                                            |
| Equivalent Series Resistance  | 90 Ohms Maximum                                        |
| Mode of Operation             | AT-Cut Fundamental                                     |
| Drive Level                   | 1mWatt Maximum                                         |
| Storage Temperature Range     | -40°C to +125°C                                        |
| Insulation Resistance         | 500 Megaohms Minimum (Measured at 100Vdc)              |

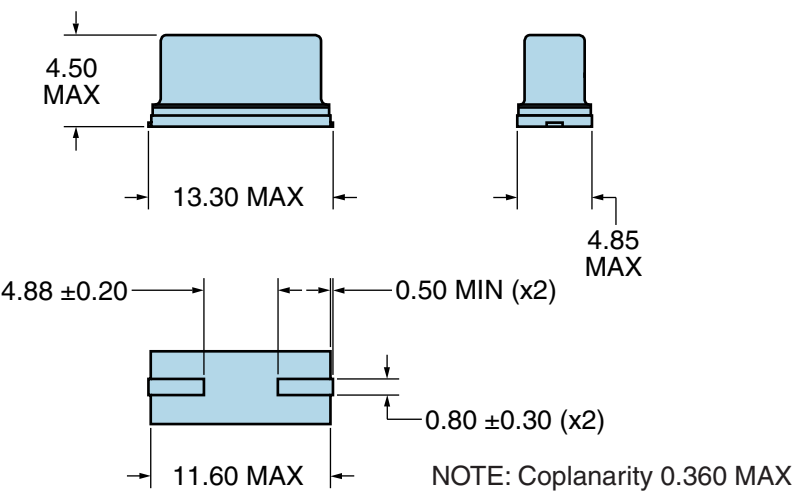
## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                              |                                               |
|------------------------------|-----------------------------------------------|
| ESD Susceptibility           | MIL-STD-883, Method 3015, Class 1, HBM: 1500V |
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A         |
| Flammability                 | UL94-V0                                       |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C         |
| Mechanical Shock             | MIL-STD-202, Method 213, Condition C          |
| Moisture Resistance          | MIL-STD-883, Method 1004                      |
| Moisture Sensitivity         | J-STD-020, MSL1                               |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K          |
| Resistance to Solvents       | MIL-STD-202, Method 215                       |
| Solderability                | MIL-STD-883, Method 2003                      |
| Temperature Cycling          | MIL-STD-883, Method 1010, Condition B         |
| Vibration                    | MIL-STD-883, Method 2007, Condition A         |

E2SMA12-8.000M

 Click part number to visit  
Part Number Details page

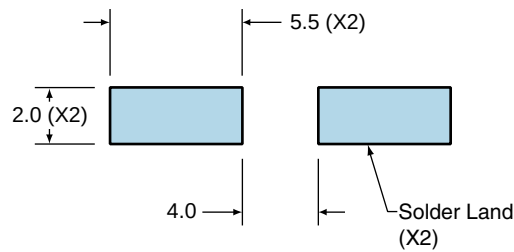
MECHANICAL DIMENSIONS (all dimensions in millimeters)



| LINE | MARKING                                         |
|------|-------------------------------------------------|
| 1    | <b>E8.0000M</b><br><i>E=Ecliptek Designator</i> |

Suggested Solder Pad Layout

All Dimensions in Millimeters

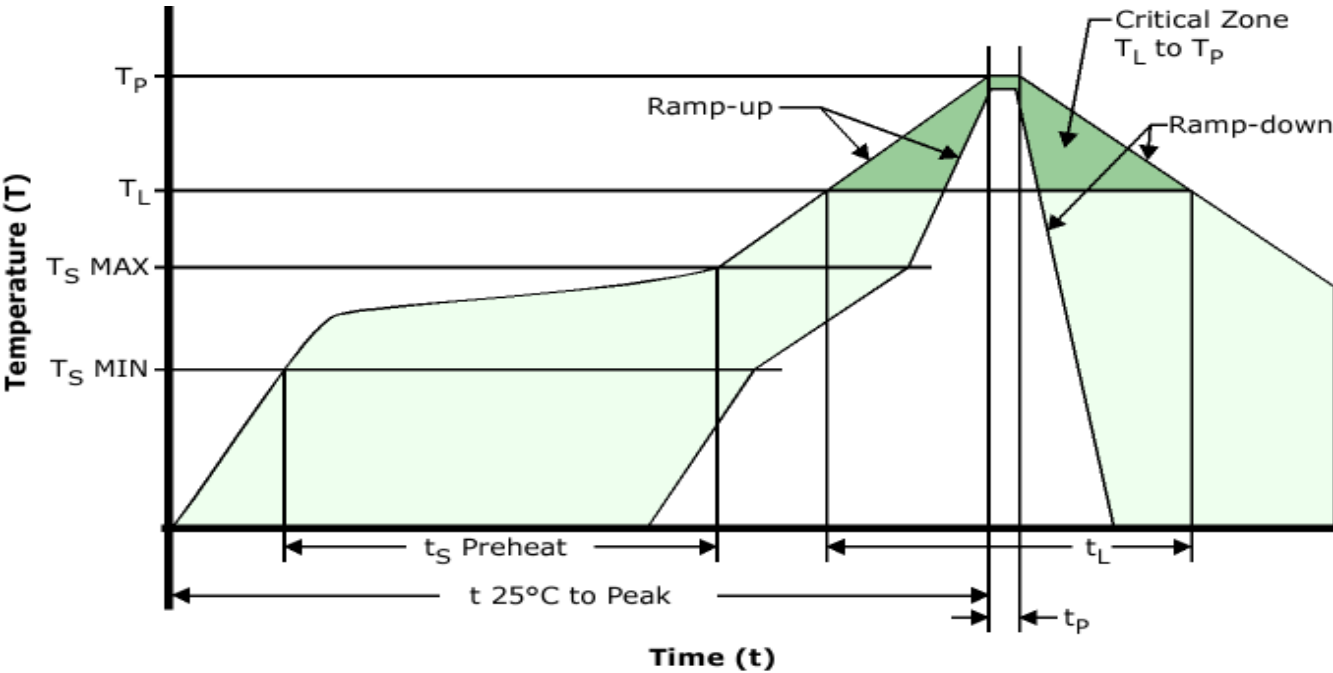


All Tolerances are ±0.1

E2SMA12-8.000M [Click part number to visit Part Number Details page](#)



Recommended Solder Reflow Methods



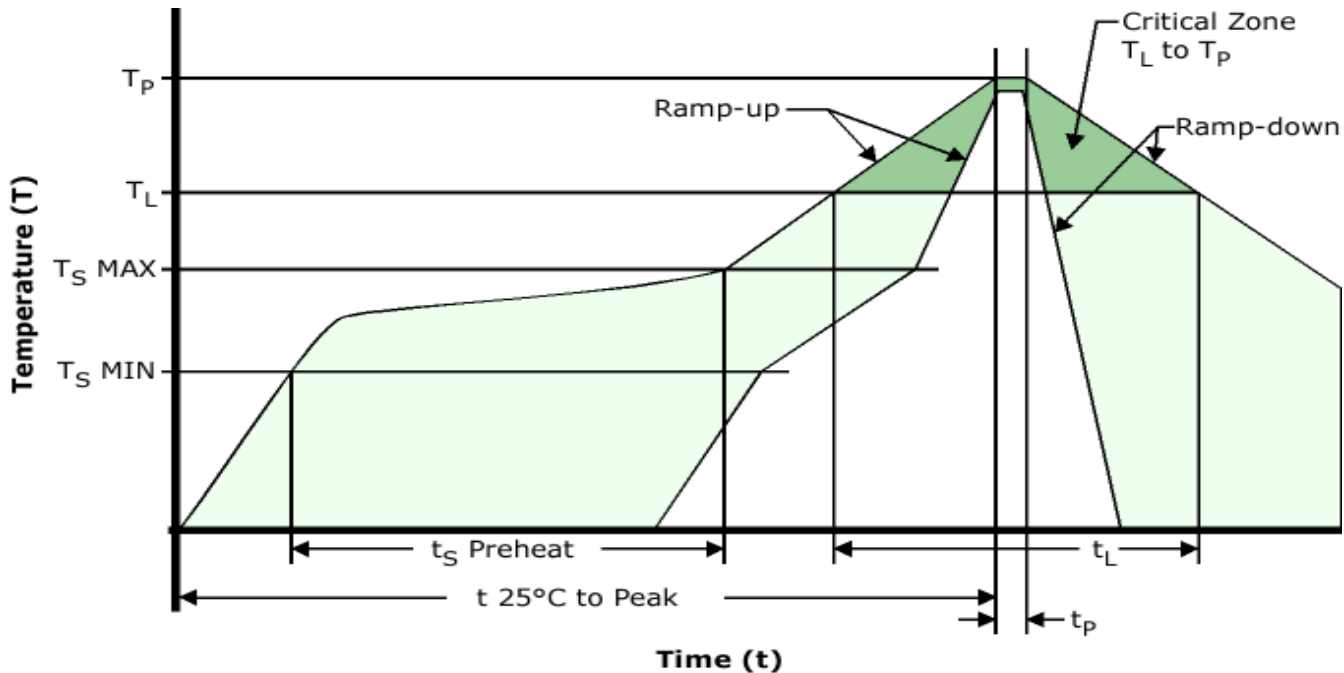
High Temperature Infrared/Convection

|                                     |                                      |
|-------------------------------------|--------------------------------------|
| Ts MAX to Tl (Ramp-up Rate)         | 3°C/Second Maximum                   |
| Preheat                             |                                      |
| - Temperature Minimum (Ts MIN)      | 150°C                                |
| - Temperature Typical (Ts TYP)      | 175°C                                |
| - Temperature Maximum (Ts MAX)      | 200°C                                |
| - Time (ts MIN)                     | 60 - 180 Seconds                     |
| Ramp-up Rate (Tl to Tp)             | 3°C/Second Maximum                   |
| Time Maintained Above:              |                                      |
| - Temperature (Tl)                  | 217°C                                |
| - Time (tl)                         | 60 - 150 Seconds                     |
| Peak Temperature (Tp)               | 260°C Maximum for 10 Seconds Maximum |
| Target Peak Temperature (Tp Target) | 250°C +0/-5°C                        |
| Time within 5°C of actual peak (tp) | 20 - 40 Seconds                      |
| Ramp-down Rate                      | 6°C/Second Maximum                   |
| Time 25°C to Peak Temperature (t)   | 8 Minutes Maximum                    |
| Moisture Sensitivity Level          | Level 1                              |

# E2SMA12-8.000M

[Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



## Low Temperature Infrared/Convection 245°C

|                                                     |                    |
|-----------------------------------------------------|--------------------|
| T <sub>S</sub> MAX to T <sub>L</sub> (Ramp-up Rate) | 5°C/Second Maximum |
|-----------------------------------------------------|--------------------|

### Preheat

|                                            |                 |
|--------------------------------------------|-----------------|
| - Temperature Minimum (T <sub>S</sub> MIN) | N/A             |
| - Temperature Typical (T <sub>S</sub> TYP) | 150°C           |
| - Temperature Maximum (T <sub>S</sub> MAX) | N/A             |
| - Time (t <sub>s</sub> MIN)                | 30 - 60 Seconds |

|                                                  |                    |
|--------------------------------------------------|--------------------|
| Ramp-up Rate (T <sub>L</sub> to T <sub>P</sub> ) | 5°C/Second Maximum |
|--------------------------------------------------|--------------------|

### Time Maintained Above:

|                                 |                     |
|---------------------------------|---------------------|
| - Temperature (T <sub>L</sub> ) | 150°C               |
| - Time (t <sub>L</sub> )        | 200 Seconds Maximum |

|                                    |               |
|------------------------------------|---------------|
| Peak Temperature (T <sub>P</sub> ) | 245°C Maximum |
|------------------------------------|---------------|

|                                                 |                                              |
|-------------------------------------------------|----------------------------------------------|
| Target Peak Temperature (T <sub>P</sub> Target) | 245°C Maximum 2 Times / 230°C Maximum 1 Time |
|-------------------------------------------------|----------------------------------------------|

|                                                  |                                                        |
|--------------------------------------------------|--------------------------------------------------------|
| Time within 5°C of actual peak (t <sub>p</sub> ) | 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time |
|--------------------------------------------------|--------------------------------------------------------|

|                |                    |
|----------------|--------------------|
| Ramp-down Rate | 5°C/Second Maximum |
|----------------|--------------------|

|                                   |     |
|-----------------------------------|-----|
| Time 25°C to Peak Temperature (t) | N/A |
|-----------------------------------|-----|

|                            |         |
|----------------------------|---------|
| Moisture Sensitivity Level | Level 1 |
|----------------------------|---------|

## Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

## High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.